

Material Composition Data

Product: GTXO-570

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Timing Is Everything

GTXO-570 - 5V SM VCTCXO Wide Pulling Range

GTXO-570 - 5V SM VCTCXO Wide Pulling Range					
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base					
	Board	BT resin		19.000	18.05
		Fibre glass	1309-37-1	38.000	36.11
	Pattern	Cu	7440-50-8	38.000	36.11
		Ni	7440-02-0	0.500	0.48
		Au	7440-57-5	0.100	0.10
	Resist ink	Resin		9.640	9.16
	Capacitor				
		Sn	7440.31-5	0.185	0.80
		Ni	7440-02-0	0.185	0.80
		Ag	7440-22-4	1.780	7.66
		TiO2	13463-67-7	16.200	69.74
		Pd	2023568	4.880	21.01
Crystal unit					
	Bonding paste	Ag	7440-22-4	0.000	0.00
	Ceramic	Al2O3	1344-28-1	28.200	45.72
	Crystal blank	SiO2	14808-60-7	0.737	1.19
	Gold plate	Au	7440-57-5	0.280	0.45
	Kovar	Fe	7439-89-6	4.320	7.00
	Metal layer	W	7440-33-7	6.210	10.07
	Nickel Plate	Ni	7440-02-0	0.800	1.30
	Nickel plating	Ni	7440-02-0	0.482	0.78
	Seam sealing	Fe	7439-89-6	6.200	10.05
	Silver low	Ag	7440-22-4	1.450	2.35
		Ni	7440-02-0	2.630	4.26
		Co	7440-48-4	1.540	2.50
		SiO2	14808-60-7	1.120	1.82
		CaO	1305-78-8	0.110	0.18
		MgO	1309-48-4	0.160	0.26
		TiO2	13463-67-7	0.310	0.50
		Mo	7439-98-7	0.190	0.31
		Co	7440-48-4	0.200	0.32
		Ni	7440-02-0	3.330	5.40
		Co	7440-48-4	1.950	3.16
		Cu	7440-50-8	0.260	0.42
		Si	7440-21-3	0.000	0.00
Lid					
	German Silver	Ni	7440-02-0	42.000	19.05
		Cu	7440-50-8	126.000	57.14
		Zn	7440-66-6	52.500	23.81
Resistor					
	Alumina board	Al2O3	1344-28-1	3.140	87.51
	Plating	Ni	7440-02-0	0.086	2.40
	Protective glass	PbO	1317-36-8	0.033	0.92
	Resistor paste	RuO2	12036-10-1	0.013	0.36
	Terminal paste	Ag	7440-22-4	0.047	1.31
		SiO2	14808-60-7	0.097	2.70
		Pd	2023568	0.004	0.11
		PbO	1317-36-8	0.005	0.14
		SiO2	14808-60-7	0.004	0.11

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
		B2O3	1303-86-2	0.000	0.00
		TiO2	13463-67-7	0.000	0.00
		PbO	1317-36-8	0.026	0.72
		SiO2	14808-60-7	0.014	0.39
		B2O3	1303-86-2	0.005	0.14
		Al2O3	1344-28-1	0.001	0.03
		SiO2	14808-60-7	0.018	0.50
		B2O3	1303-86-2	0.007	0.20
		Al2O3	1344-28-1	0.002	0.06
		Sn	7440.31-5	0.086	2.40

Solder cream					
		Sn	7440.31-5	19.300	96.50
		Ag	7440-22-4	0.600	3.00
		Cu	7440-50-8	0.100	0.50

Thermistor					
		Mn3O4	1317-35-7	0.640	22.86
		Co3O4	1308-06-1	1.010	36.07
		PbO	1317-36-8	0.162	5.79
		SiO2	14808-60-7	0.096	3.43
		B2O3	1303-86-2	0.006	0.21
		Ag	7440-22-4	0.280	10.00
		Pd	2023568	0.030	1.07
		Ni	7440-02-0	0.196	7.00
		Sn	7440.31-5	0.364	13.00

Transistor					
	Element	Si	7440-21-3	0.096	1.71
		Au	7440-57-5	0.010	0.18
	Frame	Fe	7439-89-6	1.100	19.65
		Ni	7440-02-0	0.782	13.97
		Cu	7440-50-8	0.252	4.50
		Other		0.022	0.39
	Others	Other		0.024	0.43
	Plating	Sn	7440.31-5	0.245	4.38
		Cu	7440-50-8	0.005	0.09
	Resin exterior	Si compound		2.130	38.04
		Sb2O3	1309-64-4	0.033	0.59
		Epoxy resin bromide	68541-56-0	0.106	1.89
		Organic phosphorus c		0.015	0.27
		Cr	7440-47-3	0.001	0.02
		Azo compound		0.015	0.27
		Other		0.742	13.25
	Wire	Au	7440-57-5	0.021	0.38

Crystal unit					
		Cr2O3 (Non-Hex)	1308-38-9	1.200	1.95

Thermistor					
		Cr2O3 (Non-Hex)	1308-38-9	0.016	0.57

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
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Total Mass:				442.636 mg	
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John Hems

John Hems
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